

HSB123

Silicon Epitaxial Planar Diode for High Speed Switching

REJ03G0546-0300

Rev.3.00

Jan 07, 2009

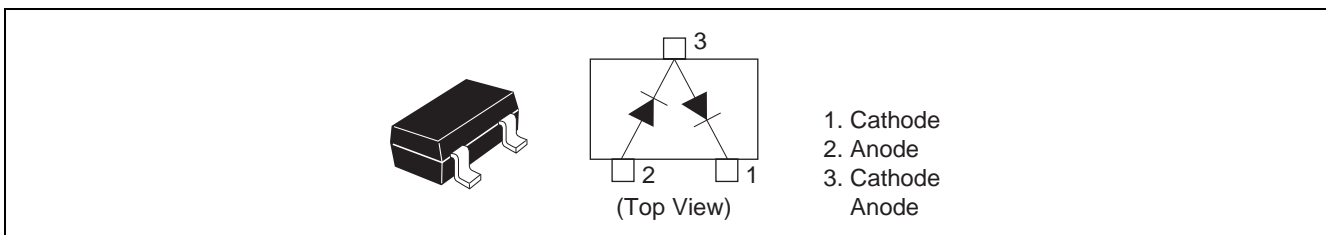
Features

- Low capacitance, proof against high voltage.
- Fast recovery time. (trr = 3.0ns max)
- CMPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Part No	Laser Mark	Package Name	Package Code	Taping Abbreviation (Quantity)
HSB123TL	A9	CMPAK	PTSP0003ZB-A	TL (3,000 pcs / reel)
HSB123TR	A9	CMPAK	PTSP0003ZB-A	TR (3,000 pcs / reel)

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Peak reverse voltage	V_{RM}	85	V
Reverse voltage	V_R	80	V
Peak forward current	I_{FM}^{*1}	300	mA
Non-Repetitive peak forward surge current	I_{FSM}^{*2}	4	A
Average rectified current	I_O^{*1}	100	mA
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

- Notes: 1. Two device total.
 2. Value at duration of 1 μ s, two device total.

Electrical Characteristics *1

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_{F1}	—	—	1.0	V	$I_F = 10$ mA
	V_{F2}	—	—	1.0	V	$I_F = 50$ mA
	V_{F3}	—	—	1.2	V	$I_F = 100$ mA
Reverse current	I_R	—	—	0.1	μ A	$V_R = 80$ V
Capacitance	C	—	—	2.0	pF	$V_R = 0$ V, $f = 1$ MHz
Reverse recovery time	t_{rr}	—	—	3.0	ns	$I_F = 10$ mA, $V_R = 6$ V, $R_L = 50$ Ω

- Note: 1. Per one device.

Main Characteristics

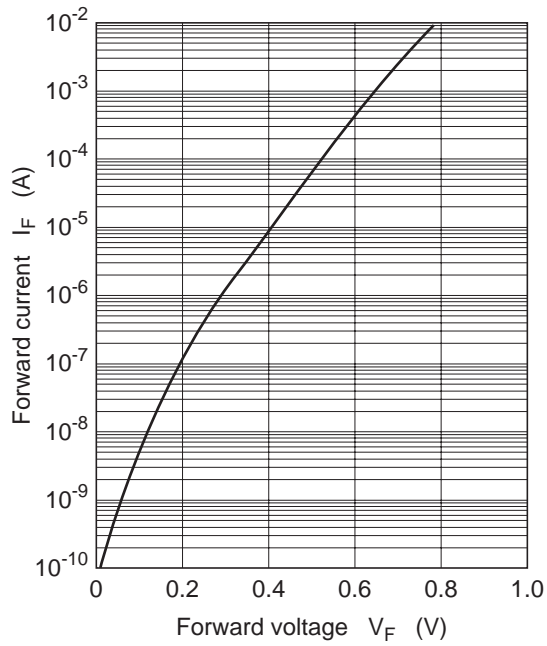


Fig.1 Forward current vs. Forward voltage

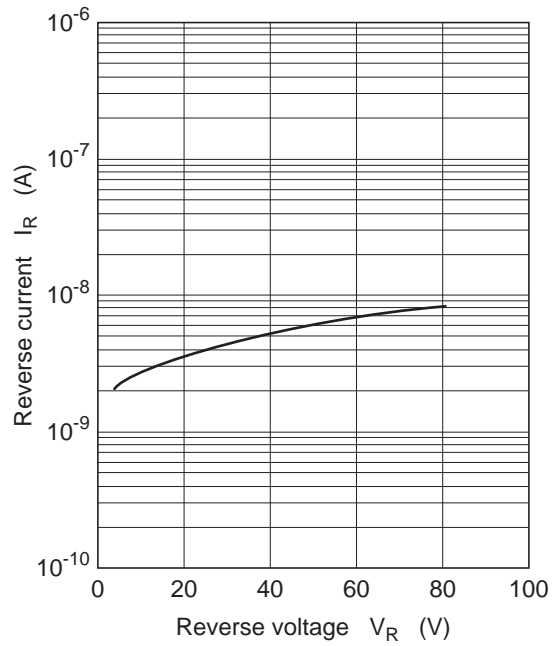


Fig.2 Reverse current vs. Reverse voltage

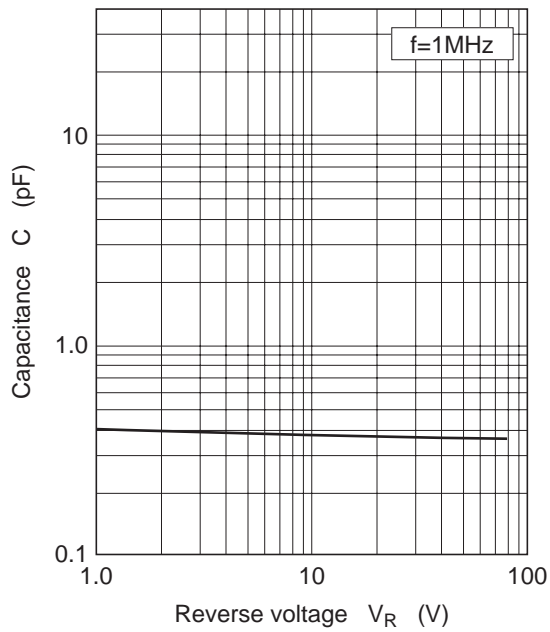
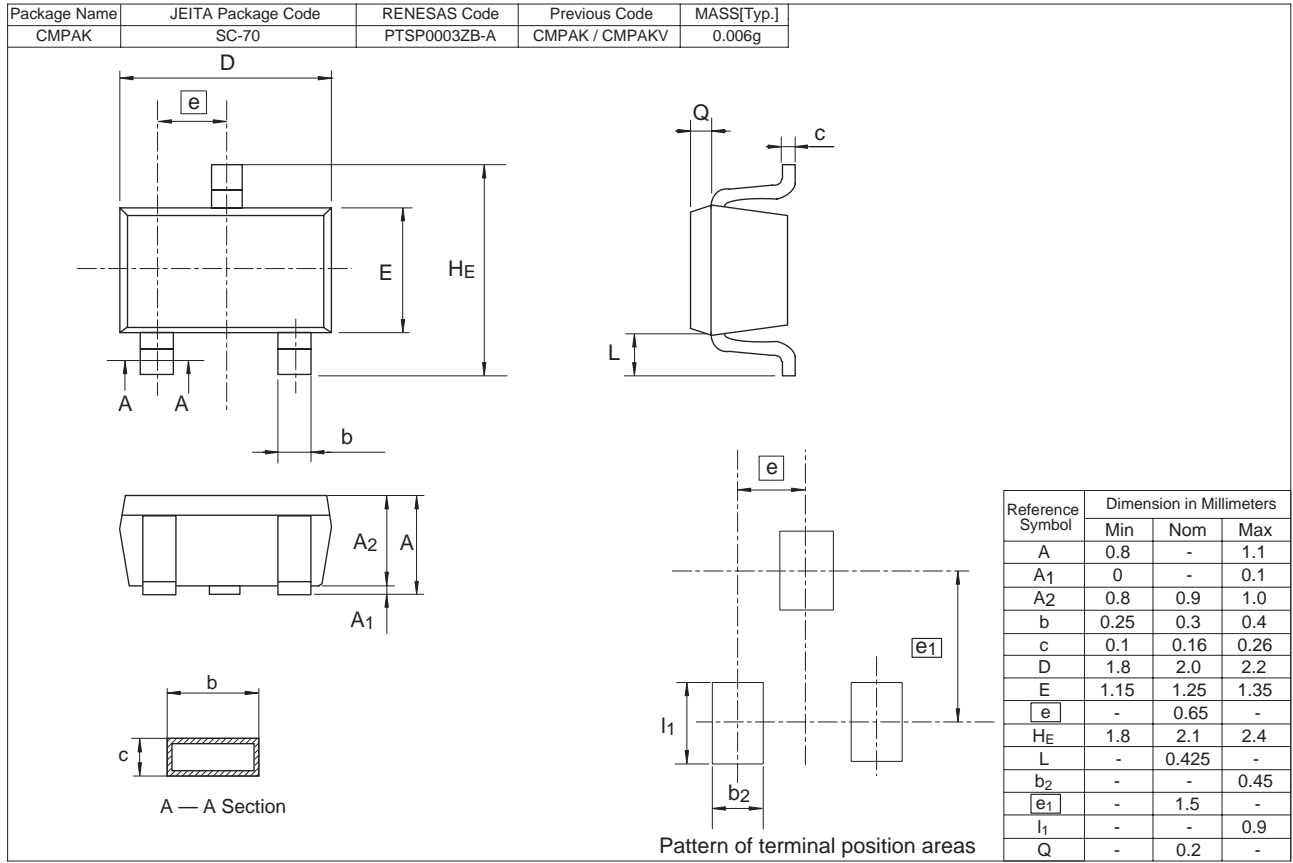


Fig.3 Capacitance vs. Reverse voltage

Package Dimensions



Notes:

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Tel: <1> (408) 382-7500, Fax: <1> (408) 382-7501

Renesas Technology Europe Limited
Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K.
Tel: <44> (1628) 585-100, Fax: <44> (1628) 585-900

Renesas Technology (Shanghai) Co., Ltd.
Unit 204, 205, AZIACenter, No.1233 Lujiazui Ring Rd, Pudong District, Shanghai, China 200120
Tel: <86> (21) 5877-1818, Fax: <86> (21) 6887-7858/7898

Renesas Technology Hong Kong Ltd.
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Tel: <852> 2265-6688, Fax: <852> 2377-3473

Renesas Technology Taiwan Co., Ltd.
10th Floor, No.99, Fushing North Road, Taipei, Taiwan
Tel: <886> (2) 2715-2888, Fax: <886> (2) 3518-3399

Renesas Technology Singapore Pte. Ltd.
1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632
Tel: <65> 6213-0200, Fax: <65> 6278-8001

Renesas Technology Korea Co., Ltd.
Kukje Center Bldg. 18th Fl., 191, 2-ka, Hangang-ro, Yongsan-ku, Seoul 140-702, Korea
Tel: <82> (2) 796-3115, Fax: <82> (2) 796-2145

Renesas Technology Malaysia Sdn. Bhd
Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jln Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
Tel: <603> 7955-9390, Fax: <603> 7955-9510